

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Fraunhofer-Gesellschaft zur Forderung der angewandten Forschung e.V.	07/22/2010
RECEIVING PARTY DATA	
Name:	Thin Material AG
Street Address:	Elsterstrasse 23
City:	Eichnau
State/Country:	GERMANY
Postal Code:	82223
PROPERTY NUMBERS Total: 2	
Property Type	Number
Application Number:	12359730
Patent Number:	7482249
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Total Attachments: 1 source=Executed_Assign#page1.tif	

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PATENT
REEL: 024794 FRAME: 0617

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

ASSIGNMENT

WHEREAS, Fraunhofer-Gesellschaft zur Förderung der angewandten Forschung e.V. (hereinafter ASSIGNOR), a corporation duly organized under the laws of Germany, located and doing business at Hansastraße 27c, München, Germany 80686 is the owner of the entire right, title and interest, by assignment recorded in the United States Patent and Trademark Office on November 18, 2005 at Reel No. 017578 Frame 0557, in the invention entitled "METHOD AND DEVICE FOR MACHINING A WAFER, IN ADDITION TO A WAFER COMPRISING A SEPARATION LAYER AND A SUPPORT LAYER," which is the subject of Letters Patent of the United States Patent No. 7,482,249, issued on January 27, 2009, and currently pending divisional application Serial No. 12/359,730, filed on January 26, 2009,

WHEREAS, Thin Material AG (hereinafter ASSIGNEE), a corporation duly organized under the laws of Germany, located and doing business at Elsterstraße 23, Eichnau, Germany 82223 is desirous of acquiring 50 % of the right, title and interest in and to the aforementioned invention and the aforementioned application and any and all Letters Patent to be obtained on said invention and/or application;


NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN:

BE IT KNOWN that for and in consideration of good and valuable consideration paid to ASSIGNOR by said ASSIGNEE, the receipt and sufficiency of which is hereby acknowledged, said ASSIGNOR, by these presents does hereby sell, assign, set over and transfer unto the said ASSIGNEE its successors, legal representatives or assigns, 50 % of the right, title and interest including the right to enforce the patent against any infringement that may have occurred before this assignment in and to the aforesaid invention in and for the United States and all countries foreign thereto; and in, to and under the aforesaid United States patent and application and any corresponding foreign applications and any divisional, continuing, substitute or reissue applications or supplementary disclosures which may be or have been filed on said invention in any country; and the right to file said foreign applications and claim priority under the provisions of the International Convention; and any Letters Patent of the United States or any foreign country issued or granted on said invention and/or said applications;

AND ASSIGNOR HEREBY covenants that it has the full right to convey 50 % of the right, title and interest herein assigned and that it has not executed and will not execute any assignment or other instrument in conflict herewith.

IN WITNESS WHEREOF, I have hereunder set my hand and seal this 22 day of

July, 2010.
Narrin Bletsch
Witness

 (LS)
Name:
Title:
On behalf of Assignor

Dr. Helmut Schubert
Head of Patents and Licensing
Fraunhofer-Gesellschaft zur Förderung
der angewandten Forschung e.V.

PATENT

RECORDED: 08/06/2010

REEL: 024794 FRAME: 0618